



Title of Change:	Qualification of ON Semiconductor, Tarlac, Philippines as Additional Test Site Location Small Package Logic Gates.	
Proposed first ship date:	27 June 2019	
Contact information:	Contact your local ON Semiconductor Sales Office or <Guy.Rahamim@onsemi.com>	
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office.	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>	
Change Part Identification:	Customer may receive the parts tested in ON Semiconductor Tarlac, Philippines from month of April 2019 once FPCN expire or earlier depending on customers' approvals. Parts tested in ON Semiconductor Philippines – Tarlac can be identified through product package labelling which follow ON Semiconductor standard.	
Change Category:	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: ON Tarlac City, Philippines	External Foundry/Subcon Sites: None
Description and Purpose:		
<p>This is a Final Product/Process Change Notification to inform customers that the final test process of the following small packages Logic devices will also be done in On Semiconductor Tarlac Philippines site. The existing test site is in Seremban Plant S1 in Malaysia. Assembly site will be retained in SBN and other subcon facilities. Product marking will be retained in the existing assembly site; thus no marking and packaging changes will be made on the affected devices as a result of this test facility change.</p> <p>The Philippines internal facility is certified with ISO/TS 16949:2009 and is currently running production for DFN and QFN package.</p> <p>There will be no change in the electrical characteristics of the involved part numbers.</p> <p>There are no product material changes as a result of this change.</p> <p>There is no product marking change as a result of this change.</p>		
Reliability Data Summary:		
Reliability Testing is not required. No Change in form, fit and function of the devices.		



Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NLU1GT125CMUTCG	NLU1GT125CMUTCG
NL17SZ125CMUTCG	NL17SZ125CMUTCG

Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle
NL17SZ125CMUTCG		NL17SZ125CMUTCG
NLU1GT125CMUTCG		NLU1GT125CMUTCG